ABSTRACT

SEMICONDUCTOR PACKAGING METHOD AND STRUCTURE THEREOF

A semiconductor packaging method includes providing a substrate having a plurality of connection pads; mounting a chip on the substrate, wherein the chip comprises a plurality of copper-containing bumps directly coupled to the connection pads, and each of the copper-containing bumps comprises a ring surface; forming an anti-dissociation gel between the substrate and the chip, wherein the anti-dissociation gel comprises a plurality of anti-dissociation substances, and the ring surfaces of the copper-containing bumps are covered by the anti-dissociation substances.

FIG. 1C